RELIABILITY REPORT

FOR

MAX9928FAUA+T

PLASTIC ENCAPSULATED DEVICES

June 9, 2014

MAXIM INTEGRATED

160 RIO ROBLES

SAN JOSE, CA 95134

Approved by
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Quality Assurance
Reliability Engineer

Conclusion

The MAX9928FAUA+T successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description

A. General

The MAX9928F/MAX9929F low-cost, uni-/bidirectional, high-side, current-sense amplifiers are ideal for monitoring battery charge and discharge currents in notebooks, cell phones, and other portable equipment. These devices feature a wide -0.1V to +28V input common-mode voltage range, low 20µA supply current with VOS less than 0.4mV, and a gain accuracy better than 1.0%. The input common-mode range is independent of the supply voltage, ensuring that the current-sense information remains accurate even when the measurement rail is shorted to ground. The MAX9928F features a current output with a transconductance ratio of 5Î¼A/mV. An external resistor converts the output current to a voltage, allowing adjustable gain so that the input sense voltage can be matched to the maximum ADC input swing. The MAX9929F has a voltage output and integrates a 10k output resistor for a fixed voltage gain of 50V/V. A digital SIGN output indicates direction of current flow, so the user can utilize the full ADC input range for measuring both charging and discharging currents. The MAX9928F/MAX9929F are fully specified over the -40°C to +125°C automotive temperature range, and available in 6-bump UCSP(tm) (1mm x 1.5mm) and 8-pin µMAX® packages. The UCSP package is bump-to-bump compatible with the MAX4372_EBT.

II. Manufacturing Information

A. Description/Function:	-0.1V to +28V Input Range, Micropower, Uni-/Bidirectional, Current-Sense Amplifiers
B. Process:	B12
C. Number of Device Transistors:	293
D. Fabrication Location:	Oregon, California or Texas
E. Assembly Location:	Philippines, Thailand
F. Date of Initial Production:	July 26, 2008

III. Packaging Information

A. Package Type:	8-pin uMAX
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-2882
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	221°C/W K.
Single Layer Theta Jc:	41.9°C/W
L. Multi Layer Theta Ja:	206.3°C/W
M. Multi Layer Theta Jc:	41.9°C/W

IV. Die Information

A. Dimensions:	62X42 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	1.2 microns (as drawn)
F. Minimum Metal Spacing:	1.2 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% for all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 48 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 22.9 \times 10^{-9}$

$\lambda = 22.9$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maximintegrated.com/qa/reliability/monitor. Cumulative monitor data for the B12 Process results in a FIT Rate of 0.05 @ 25C and 0.92 @ 55C (0.8 eV, 60% UCL).

B. E.S.D. and Latch-Up Testing (lot JHLZBQ002G D/C 1329)

The OY28 die die type has been found to have all pins able to withstand a transient pulse of:

ESD-HBM:	+/- 2500V per JEDEC JESD22-A114
ESD-CDM:	+/- 750V per JEDEC JESD22-C101

Latch-Up testing has shown that this device withstands a current of +/-100mA, -70mA for SIGN pin and overvoltage per JEDEC JESD78 .

Table 1
Reliability Evaluation Test Results

MAX9928FAUA+T

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	48	0	JHLWBQ001B, D/C 0822

Note 1: Life Test Data may represent plastic DIP qualification lots.